

ECIA Industry Alert: Tariffs

The ECIA Global Industry Practices Committee (GIPC) has compiled the following resources to update members on the ongoing tariff changes that have impacted the component industry so profoundly. While recognizing the need to balance global trade and support U.S. manufacturing, [ECIA has taken the position](#) that tariffs have imposed significant and uneven challenges on the component channel. ECIA is committed to monitoring the situation. To that end, we are issuing this latest Industry Alert.



The U.S. Customs and Border Protection agency issued a guidance statement regarding [President Trump's January 14, 2026, Proclamation](#), pursuant to Section 232 of the Trade Expansion Act of 1962, as amended (19 U.S.C. 1862), which imposes 25 percent ad valorem duties on certain imports of semiconductors and their derivative products.

[U.S. Customs and Border Protection message](#) “provides guidance for importers, brokers, and filers.”

Key Points

- The U.S. Department of Commerce issued a rule newly permitting certain advanced, H200/MI325X-grade computing chips classified under Export Control Classification Number (ECCN) 3A090 to be eligible for export to China, subject to a case-by-case licensing policy instead of a policy of denial.
- In order to be eligible for the case-by-case licensing policy, chips must undergo U.S.-based testing, and exporters must provide additional certifications or verifications regarding the performance criteria, supply, and end use(r) prior to export to China.
- In concert, the U.S. government enacted a 25 percent Section 232 tariff on the import of this merchandise, creating an avenue for the U.S. government to obtain a cut of permitted sales. Exceptions to this new tariff policy will permit U.S. data centers, start-ups, and certain other tech users to continue importing these items without incurring this cost.

[SOURCE: Wilson Sonsini Law blog](#)

According to Wilson Sonsini, “While the export changes outlined above reflect a significant opening up of advanced computing chip commodities to China, newly authorized exporters will pay a cost to engage in such exports, as will non-privileged importers. The new 25% Section 232 semiconductor tariff that CBP implemented in accordance with the Semiconductor Tariff Proclamation follows the Office of the U.S. Trade Representative’s Section 232 investigation into the national security implications of U.S. imports of certain foreign-produced semiconductor items.”³

“Specifically, this new Section 232 tariff of 25 percent reaches items classifiable under subheadings 8471.50, 8471.80, and 8473.30 of the Harmonized Tariff Schedule of the United States (HTSUS) meeting the following performance parameters:

- (1) a TPP greater than 14,000 and less than 17,500, and a total DRAM bandwidth greater than 4,500 GB/s and less than 5,000 GB/s; or
- (2) a TPP greater than 20,800 and less than 21,100, and total DRAM bandwidth greater than 5,800 GB/s and less than 6,200 GB/s.

“These performance parameters are designed to capture advanced semiconductor commodities such as the H200 and MI325X, leading chips designed by the U.S.’s largest chip companies.”

Companies that want more guidance are instructed to contact the Trade Remedy Branch at TradeRemedy@cbp.dhs.gov.

ECIA members should be reviewing their current responses and assessing the [Harmonized Tariff Schedule of the US](#) for specifics and exemptions.

[Price Waterhouse Cooper has issued a useful general summary resource.](#)

Finally, please refer to [ECIA’s Global Industry Practices page on Tariffs](#).